

REMARKS

Reconsideration of this application in light of the present amendment and remarks is respectfully requested.

Claims 1, 2, 4, 5 and 7 have been rejected.

Claims 11, 12, 27 and 28 were previously withdrawn.

Claims 3 and 7 have been cancelled.

Claims 6, 8-10 and 13-26 were previously cancelled.

Claim 1 has been amended.

Claims 1, 2, 4 and 5 are pending in this application.

Claim 3 was objected to as referring to withdrawn subject matter.

Claim 3 has been canceled, thereby rendering this objection moot.

Claims 1, 2, 4, 5 and 7 were rejected under 35 U.S.C. §112, first paragraph, as failing to comply with the written description requirement. Claim 1 has been amended to remove the objectionable "second cure" reference. Claim 7 has been canceled. Claims 2, 4 and 5 are dependent on claim 1, and now have the objectionable material removed by reference thereto.

Therefore, applicant respectfully requests that the Examiner withdraw this rejection.

Claims 1, 4 and 7 have been rejected under 35 U.S.C. §103(a) as being unpatentable over Jensen et al (US 5,896,271), in view of Williams et al (US 5,378,298), and any one of Derwent Abstract of South African patent 317040, Japanese Patent 2-34987 or Leonard et al (US 6,071,371), further taken with any one of Fisher et al (US 5,216,581), Meny et al (US 5,170,326), or Cottingham et al (US 5,103,375). This rejection is respectfully traversed.

Claim 7 has been canceled.

Independent claim 1 has been amended to incorporate the features of: use of a flexible circuit board (from claim 7, subsequently canceled); first curing selected areas of the adhesive (from claim 3, subsequently canceled); and supplying a thermal path through the adhesive. Support for this can be found in claim 3 and in the specification on page 7, line 4-11. It is believed that the combination of selective curing and of pressing the board into the adhesive to provide a thermal path is novel and unobvious of the cited art.

Therefore, applicants respectfully submit that amended claim 1 is now deemed allowable for the above reasons.

Claim 4 is dependent on amended claim 1, and the above comments with respect to claim 1 are hereby incorporated by reference. Therefore, claim 4 is deemed allowable as well for the same reasons.

Accordingly, for the reasons set forth above, the Applicants respectfully request withdrawal of the rejection based on the cited references.

Claim 2 has been rejected under 35 U.S.C. §103(a) as being unpatentable the references as set forth above and further taken with any one of Bluem et al (US 6,214,460), Masayuki et al (US 6,649,012), or Banovetz et al (US 2002/0004132). This rejection is respectfully traversed.

Claim 2 is dependent on amended claim 1, and the above comments with respect to claim 1 are hereby incorporated by reference. Therefore, claim 2 is deemed allowable as well for the same reasons.

Accordingly, for the reasons set forth above, the Applicants respectfully request withdrawal of the rejection based on the cited references.

Claim 2 has been rejected under 35 U.S.C. §103(a) as being unpatentable over the references set forth above and further taken with any one of Bluem et al, Masayuki et al, or Banovetz et al. This rejection is respectfully traversed.

Claim 2 is dependent on amended claim 1, and the above comments with respect to claim 1 are hereby incorporated by reference. Therefore, claim 2 is deemed allowable as well for the same reasons.

Accordingly, for the reasons set forth above, the Applicants respectfully request withdrawal of the above rejection.

Claims 1, 4 and 7 have been rejected under 35 U.S.C. §103(a) as being unpatentable the references as set forth above and further taken with Chipbonding Adhesive or Dual Cure System Adhesives.

Claim 7 has been canceled.

Claims 1 and 4 are dependent on amended claim 1, and the above comments with respect to claim 1 are hereby incorporated by reference. Therefore, claims 4 and 6 are deemed allowable as well for the same reasons.

Accordingly, for the reasons set forth above, the Applicants respectfully request withdrawal of the above rejection.

Claim 5 has been rejected under 35 U.S.C. §103(a) as being unpatentable the references as set forth above and further taken with McIver et al (US 4,396,936). This rejection is respectfully traversed.

Claim 5 is dependent on amended claim 1, and the above comments with respect to claim 1 are hereby incorporated by reference. Therefore, claim 5 is deemed allowable as well for the same reasons.

Accordingly, for the reasons set forth above, the Applicants respectfully request withdrawal of the above rejection.

### **Conclusion**

The other references of record have been reviewed and applicant's invention is deemed patentably distinct and nonobvious over each taken alone or in combination.

For the foregoing reasons, applicants respectfully request that the above rejections be withdrawn.

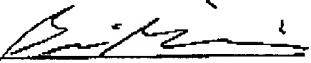
Inasmuch as this amendment distinguishes all of the applicants' claims over the prior art references, for the many reasons indicated above, passing of this case is now believed to be in order. A Notice of Allowance is earnestly solicited.

No amendment made was related to the statutory requirements of patentability unless expressly stated herein. No amendment made was for the purpose of narrowing the scope of any claim, unless applicant has argued herein that such amendment was made to distinguish over a particular reference or combination of references.

In the event that the Examiner deems the present application non-allowable, it is requested that the Examiner telephone the Applicants' attorney at the number indicated below so that the prosecution of the present case may be advanced by the clarification of any continuing rejection or through an Examiner's amendment.

Authorization is hereby given to charge any fees necessitated by actions taken herein to  
Deposit Account 50-2117.

Respectfully submitted,  
Jiao et al.

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